

IN THE CLAIMS:

1. (Original) A thermoconductive addition-curable liquid silicone rubber composition having a thermal conductivity of at least 0.3 W/(m·K) after curing which comprises

- (A) 100 parts by weight of liquid diorganopolysiloxane that has a viscosity of 100 to 100,000 mPa·s and contains at least two silicon-bonded alkenyl groups in each molecule,
- (B) 50 to 600 parts by weight of alumina micropowder that has an average particle size of 0.1 to 50 μm ,
- (C) 20 to 100 parts by weight of iron oxide micropowder that has an average particle size of 0.01 to 0.5 μm ,
- (D) 0.1 to 2.0 parts by weight of cerium oxide micropowder, cerium hydroxide micropowder, or cerium-containing heteroorganosiloxane,
- (E) organopolysiloxane that contains at least two silicon-bonded hydrogen atoms in each molecule, wherein the component (E) content provides from 0.3 to 5 moles silicon-bonded hydrogen in component (E) per 1 mole silicon-bonded alkenyl in component (A), and
- (F) platinum catalyst in a catalytic quantity.

2. (Original) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 1 characterized in that the particle shape of the alumina micropowder (B) is spherical or irregular.

3. (Currently Amended) A thermoconductive addition-curable liquid silicone rubber composition in accordance with ~~any preceding~~ claim 1 characterized in that the surface of the alumina micropowder (B) has been treated with a surface treatment agent.

4. (Currently Amended) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 3 characterized in that the surface treatment agent is an organoalkoxysilane, a tetraalkoxysilane, or a partial hydrolysis and/or condensation product of tetraalkoxysilane.

5. (Currently Amended) A thermoconductive addition-curable liquid silicone rubber composition in accordance with ~~any preceding~~ claim 1 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).

6. (Currently Amended) A thermoconductive addition-curable liquid silicone rubber composition in accordance with ~~any preceding~~ claim 1 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

7. (Currently Amended) Use of a thermoconductive addition-curable liquid silicone rubber composition according to ~~any preceding~~ claim 1 in a fixing roll for electrophotographic copiers, electronic printers ~~[[and]]~~ or facsimile machines.

8. (Currently Amended) Use in accordance with claim 7 wherein ~~[[said]]~~ the fixing roll is a coated fixing roll comprising a fluororesin layer or a fluororubber layer disposed on the peripheral surface of a roll shaft, with ~~[[said]]~~ the thermoconductive addition-curable liquid silicone rubber composition interposed between the fluororesin layer and the roll shaft.

9. (Currently Amended) A coated fixing roll comprising a fluororesin layer or a fluororubber layer disposed on the peripheral surface of a roll shaft, and a silicone rubber layer interposed between the fluororesin layer or the fluororubber layer and the roll shaft, the ~~[[which]]~~ silicone rubber layer being the cured product of the thermoconductive addition-curable liquid silicone rubber composition ~~in accordance with any one of claims 1 to 6 of claim 1.~~

Please add the following new claims.

10. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 2 characterized in that the surface of the alumina micropowder (B) has been treated with a surface treatment agent.

11. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 10 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).
12. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 2 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).
13. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 3 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).
14. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 4 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).
15. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 2 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).
16. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 3 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).
17. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 4 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

18. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 5 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

19. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 10 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

20. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 11 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).